



Hysol[®] PC30STD

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PRODUCT DESCRIPTION

Hysol[®] PC30STD is a waterborne acrylic, one component coating recommended for printed board coating. PC30STD is a stable material, suitable for continuous operation up to 100°C. It may be applied by brush, dip or spray to electrical parts, for improved moisture and environmental protection. Components and joints may be repaired, by heating the coating with a soldering iron, for easy removal. When fully cured, PC30STD exhibits superior toughness and abrasion resistance. Even after long exposure to the elements, the coating retains its very light color.

TYPICAL UNCURED PROPERTIES

Color	Off White
Flash Point, °C	62.8
Solids Content, %, weight	36
Specific Gravity @ 25°C	1.0
Viscosity @ 25°C, Brookfield RVF Spindle 2, Speed 20, cps, max.	380
Shelf Life @ 25°C, months from date of manufacture (unopened)	12
VOC, gms/liter	127

TYPICAL CURED PROPERTIES

Values are not intended for use in the preparation of specifications. All measurements are taken at 25°C, unless otherwise noted.

Appearance – No blistering, wrinkling, cracking or peeling of film. No discoloration of printed conductors or substrate after thermal shock, or after moisture resistance testing.

Ruggedization – No cracking or crazing with vibration.

Film Thickness – Adjustable from 0.001 to 0.003 inches.

Fluorescent – When viewed under ultraviolet light (black light).

TYPICAL CURED ELECTRICAL PROPERTIES

Dielectric Strength, volts/mil	860
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HANDLING

Printed circuits or other objects to be coated should be cleaned in accordance with accepted industry practices. Isopropyl alcohol, P.C. freon or methyl ethyl ketone have been found satisfactory as cleaning agents.

Applications should be performed in a well-ventilated area. It is also recommended that Hysol bulletin entitled "Suggested Precautions for Handling HYSOL Liquid Products" be read.

Air dry coated boards at least 30 minutes at 25°C (77°F) to remove solvents before curing in oven or before applying additional coats.

CURE SCHEDULE

Recommended cure – two hours at 60°C (140°C) in an oven. Alternate cure – at room temperature and average relative humidity to (30% to 50%):

Tack free, hours	1
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Semi-hard film, days	1
Optimum properties, days	7

Some variation in listed values may occur; customer should determine whether cure other than recommended cure above will give satisfactory results.

Apply by brush, dip or spray for 1 to 2 mil film. Cleanliness of the substrate is paramount in promoting adhesion and preventing under-film corrosion of copper conductors.

Viscosity may be reduced when desired with deionized water, or by using xylene. AC0305 is not recommended..

Keep containers closed to avoid contamination. Contents may solidify. Store above 40°F (4°C), and below 80°F (26°C).

Matthias

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

STORAGE

Liquid Storage – Liquids should be stored at 23°C or below, in closed containers. If stored below 23°C, the material MUST be allowed to come to room temperature, in the sealed container, to avoid moisture contamination.

DATA RANGES

The data contained herein may be reported as a typical value and/or range values based on actual test data and are verified on a periodic basis.

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Loctite Corporation's products. Henkel Loctite Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Loctite Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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